

1. Product Overview

WBR3D is a low-power embedded Wi-Fi and Bluetooth module that Tuya has developed. It consists of a highly integrated RF chip (RTL8720DN) and several peripheral components, with an embedded Wi-Fi network protocol stack, Bluetooth network protocol, and robust library functions. WBR3D is embedded with a low-power 32-bit CPU, 512 KB static random-access memory (SRAM), and 4 MB flash memory, and has extensive peripherals.

WBR3D is an RTOS platform that integrates all function libraries of the Wi-Fi MAC and TCP/IP protocols. You can develop embedded Wi-Fi products as required.

1.1 Features

- ✧ Embedded low-power 32-bit CPU, which can also function as an application processor
 - Dominant frequency: up to 200 MHz
- ✧ Working voltage: 3.0 V to 3.6 V
- ✧ Peripherals: eight GPIOs, one universal asynchronous receiver/transmitter (UART), and one analog-to-digital converter (ADC)
- ✧ Wi-Fi connectivity
 - 802.11a/b/g/n 1T1R, 2.4 GHz and 5 GHz capable
 - Channels 1 to 14 at 2.4 GHz and channels 36 to 177 at 5 GHz
 - WPA and WPA2 security modes
 - Up to +19 dBm output power in 802.11b mode and up to +16 dBm in 802.11a mode
 - STA, AP, and STA+AP working modes

- Smart and AP network configuration modes for Android and iOS devices
- Onboard PCB antenna with 2 dBi at 2.4 GHz and 2.6 dBi at 5 GHz
- Working temperature: -20°C to +85°C

1.2 Applications

- ✧ Intelligent building
- ✧ Smart household and home appliances
- ✧ Smart socket and light
- ✧ Industrial wireless control
- ✧ Baby monitor
- ✧ Network camera
- ✧ Intelligent bus

Change History

No.	Date	Change Description	Version After Change
1	2019-08-30	This is the first release.	1.0.0

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2. WBR3D Label



Model: module model

P/N: product number

S/N: serial number

CE: European Conformity marking

RoHS: RoHS compliance logo

3. Module Interfaces

3.1 Dimensions and Footprint

WBR3D has two rows of pins with a 2 mm pin spacing.

The WBR3D dimensions (H x W x D) are 3.5 mm x 16 mm x 24 mm. Figure 3-1 shows the front and rear views.

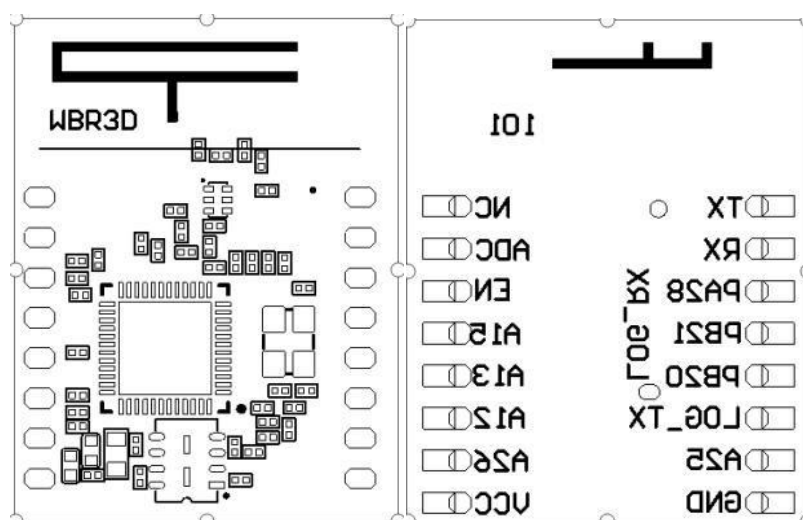


Figure 3-1 WBR3D front and rear views

Note:

The common appearance tolerance is ± 0.3 mm. The tolerance of positions that involve plug-in assembly is ± 0.1 mm. The thickness tolerance of a 1 mm thick PCB is ± 0.1 mm.

3.2 Interface Pin Definition

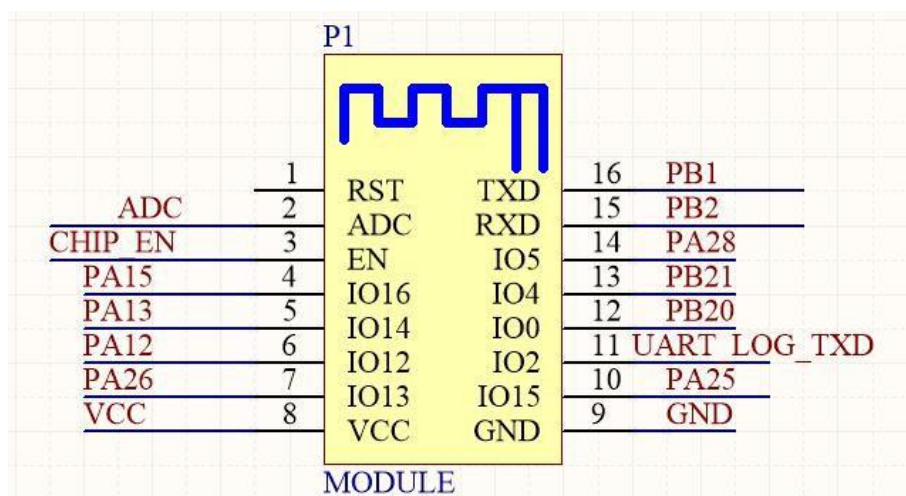


Table 3-1 WBR3D interface pins

Pin No.	Symbol	I/O Type	Function
1	RST	I/O	Hardware reset pin (The module has an internal pull-up resistor, and the reset pin is active at a low level.)
2	ADC	AI	10-bit precision SAR ADC (See the following Note 2.)
3	EN	Input	Module enabling pin, which is connected to 3.3 V for normal use
4	GPIO16	I/O	GPIO_16, which needs to be connected to a 10-kiloohm pull-up resistor when being used
5	GPIO14	I/O	GPIO_14
6	GPIO12	I/O	GPIO_12
7	GPIO13	I/O	GPIO_13
8	VCC	P	Power supply pin (3.3 V)
9	GND	P	Power supply reference ground pin
10	GPIO15	Output	GPIO_15 (used during module power-on and initialization; use it with caution)

Pin No.	Symbol	I/O Type	Function
11	GPIO2	Output	UART0_TXD (used to display the module internal information)
12	GPIO0	I/O	GPIO_0 (used during module power-on and initialization; use it with caution)
13	GPIO4	I/O	GPIO_04
14	GPIO5	I/O	GPIO_05
15	RXD0	I/O	UART0_RXD (See the following Note 3.)
16	TXD0	Output	UART0_TXD (See the following Note 3.)

Note:

1. **P** indicates power supply pins, **I/O** indicates input/output pins, and **AI** indicates analog input pins. RST is only a hardware reset pin and cannot clear the Wi-Fi network configuration.
2. This pin can only function as an ADC input and not a common I/O. If this pin is not used, it must be disconnected. When this pin is used as the ADC input, the input voltage range is 0 V to 1.0 V.
3. UART0 is a user-side serial interface, which generates information when the module is powered on and starts.

3.3 Test Pin Definition

Table 3-2 WBR3D test pins

Pin No.	Symbol	I/O Type	Function
N/A	TEST	Input	Used for the module production test

Note:

Test pins are not recommended.

4. Electrical Parameters

4.1 Absolute Electrical Parameters

Table 4-1 Absolute electrical parameters

Parameter	Description	Minimum Value	Maximum Value	Unit
Ts	Storage temperature	-20	85	°C
VCC	Power supply voltage	-0.3	3.6	V
Static electricity voltage (human body model)	Tamb = 25°C	N/A	2	kV
Static electricity voltage (machine model)	Tamb = 25°C	N/A	0.5	kV

4.2 Electrical Conditions

Table 4-2 Normal electrical conditions

Parameter	Description	Minimum Value	Typical Value	Maximum Value	Unit
Ta	Working temperature	-20	N/A	85	°C
VCC	Power supply voltage	3.0	3.3	3.6	V
V _{IL}	I/O low-level input	-0.3	N/A	VCC x 0.25	V
V _{IH}	I/O high-level input	VCC x 0.75	N/A	VCC	V
V _{OL}	I/O low-level output	N/A	N/A	VCC x 0.1	V

Parameter	Description	Minimum Value	Typical Value	Maximum Value	Unit
V _{OH}	I/O high-level output	VCC x 0.8	N/A	VCC	V
I _{max}	I/O drive current	N/A	N/A	12	mA

4.3 RF Current

Table 4-3 Current during constant transmission and receiving

Working Status	Parameter			Typical Value	Unit
	Mode	Rate	TX Power/Receiving		
TX at 2.4 GHz	802.11b	11 Mbit/s	+18 dBm	250	mA
	802.11g	54 Mbit/s	+17 dBm	180	mA
	802.11n	HT20 MCS7	+16 dBm	170	mA
	802.11n	HT40 MCS7	+16 dBm	150	mA
TX at 5 GHz	802.11g	54 Mbit/s	+15 dBm	300	mA
	802.11n	HT20 MCS0	+15 dBm	230	mA
	802.11n	HT20 MCS7	+14 dBm	220	mA

4.4 Working Current

Table 4-4 WBR3D working current

Working Mode	Working Status (Ta = 25°C)	Average Value	Maximum Value	Unit
EZ	The module is in EZ mode, and the Wi-Fi indicator blinks quickly.			mA
AP	The module is in AP mode, and the Wi-Fi indicator blinks slowly.			mA

Working Mode	Working Status (Ta = 25°C)	Average Value	Maximum Value	Unit
Connected	The module is connected to the network, and the Wi-Fi indicator is steady on.			mA
Disconnected	The module is disconnected from the network, and the Wi-Fi indicator is steady off.			mA

5. RF Features

5.1 Basic RF Features

Table 5-1 Basic RF features

Parameter	Description
Frequency band	2.412 GHz to 2.484 GHz; 5.18 GHz to 5.825 GHz
Wi-Fi standard	IEEE 802.11a/b/g/n (Channels 1 to 14 and 36 to 177) (Ch 1-13 for CE, Ch 1-11 for FCC)
Data transmission rate	802.11b: 1, 2, 5.5, or 11 (Mbit/s) 802.11a/g: 6, 9, 12, 18, 24, 36, 48, or 54 (Mbit/s) 802.11n: HT20 MCS0 to MCS7 802.11n: HT40 MCS0 to MCS7
Antenna type	PCB antenna with a gain of 2 dBi at 2.4 GHz and 2.6 dBi at 5 GHz

5.2 TX Performance

Table 5-2 Performance during constant transmission at 2.4 GHz

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
Average RF output power, 802.11b CCK mode	11 Mbit/s	N/A	17	N/A	dBm

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
Average RF output power, 802.11g OFDM mode	54 Mbit/s	N/A	16	N/A	dBm
Average RF output power, 802.11n HT20 mode	MCS7	N/A	15	N/A	dBm
Average RF output power, 802.11n HT40 mode	MCS7	N/A	14	N/A	dBm
Frequency error		−10	N/A	+10	ppm
EVM under 802.11b CCK, 11 Mbit/s, 17.5 dBm		N/A	−16.5	N/A	dB
EVM under 802.11g OFDM, 54 Mbit/s, 15.0 dBm		N/A	−33.1	N/A	dB
EVM under 802.11n OFDM, MCS7, 14.0 dBm		N/A	−32.2	N/A	dB

Table 5-3 Performance during constant transmission at 5 GHz

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
Average RF output power, 802.11a OFDM mode	54 Mbit/s	N/A	14	N/A	dBm
Average RF output power, 802.11n HT20 mode	MCS7	N/A	13	N/A	dBm
Average RF output power, 802.11n HT40 mode	MCS7	N/A	12	N/A	dBm
Frequency error		−10	N/A	+10	ppm
EVM under 802.11b CCK, 11 Mbit/s, 17.5 dBm		N/A	−16.5	N/A	dB
EVM under 802.11g OFDM, 54 Mbit/s, 15.0 dBm		N/A	−33.1	N/A	dB
EVM under 802.11n OFDM, MCS7, 14.0 dBm		N/A	−32.2	N/A	dB

5.3 RX Performance

Table 5-4 RX sensitivity

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
PER < 8%, 802.11b CCK mode	11 Mbit/s	N/A	−91	N/A	dBm
PER < 10%, 802.11a/g OFDM mode	54 Mbit/s	N/A	−75	N/A	dBm
PER < 10%, 802.11n OFDM mode	HT20 MCS7	N/A	−72	N/A	dBm

6. Antenna Information

6.1 Antenna Type

WBR3D uses an onboard PCB antenna.

6.2 Antenna Interference Reduction

To ensure optimal Wi-Fi performance when the Wi-Fi module uses an onboard PCB antenna, it is recommended that the antenna be at least 15 mm away from other metal parts.

To prevent adverse impact on the antenna radiation performance, avoid copper or traces along the antenna area on the PCB. Ensure that there are no substrate media above or below the antenna and that copper is at a certain distance away from the antenna to maximize the antenna radiation performance.

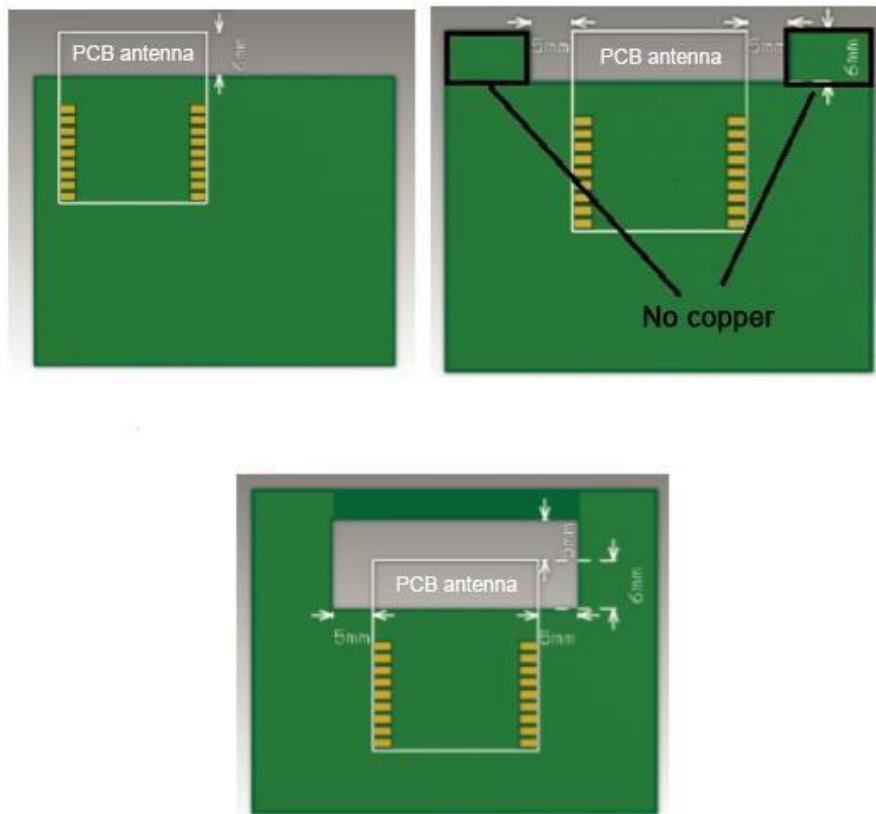


Figure 6-1 Antenna placement

For details about the onboard PCB antenna area on WBR3D, see Figure 7-1.

6.3 Antenna Connector Specifications

WBR3D does not use an antenna connector.

7. Packaging Information and Production Instructions

7.1 Mechanical Dimensions

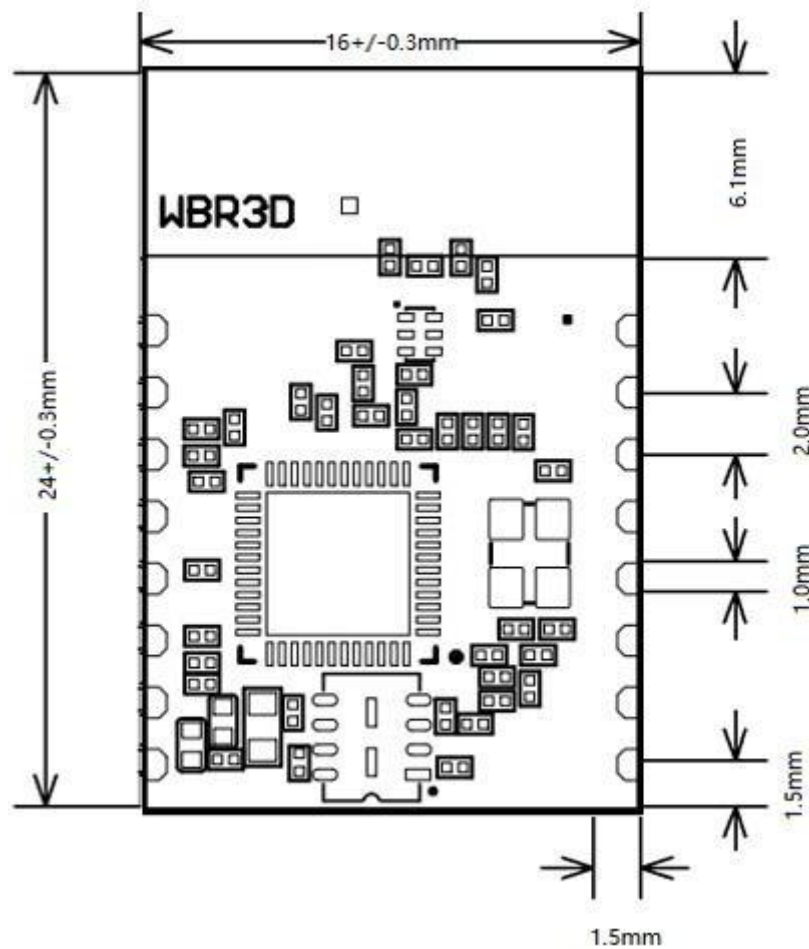


Figure 7-1 WBR3D mechanical dimensions

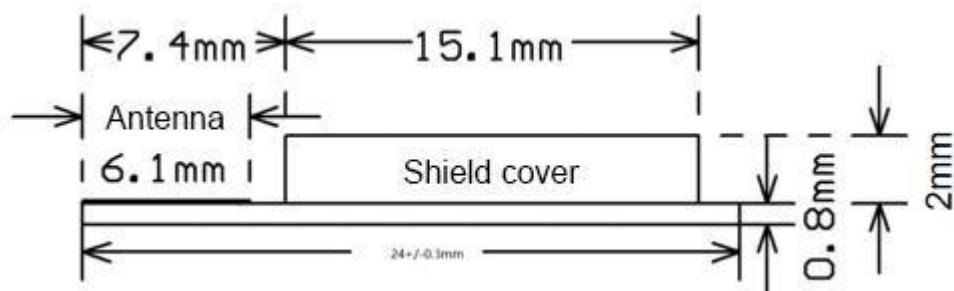


Figure 7-2 Side view

The default dimensional tolerance is ± 0.3 mm. If a customer has other requirements, clearly specify them in the datasheet after communication.

7.2 Recommended PCB Encapsulation

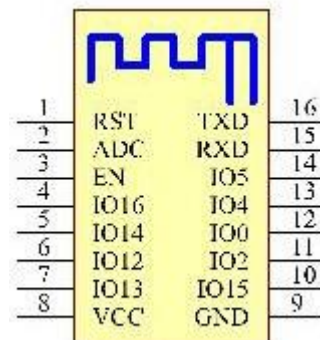


Figure 7-3 WBR3D pins

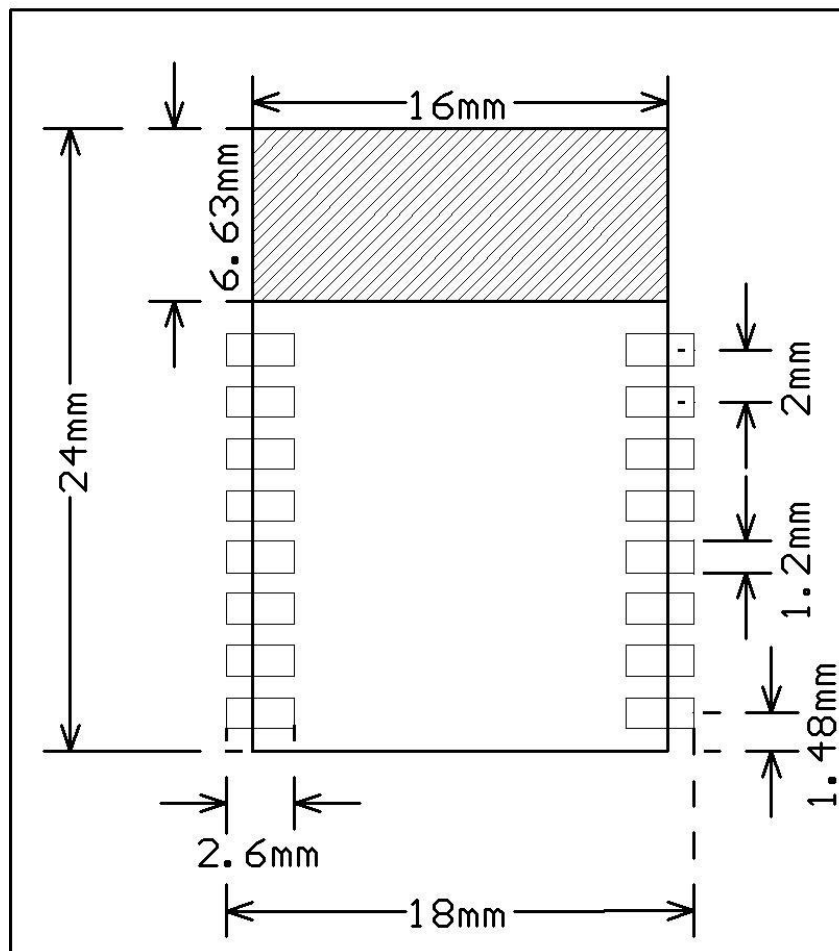


Figure 7-4 PCB encapsulation diagram of WBR3D

7.3 Production Instructions

1. Use an SMT placement machine to mount components to the stamp hole module that Tuya produces within 24 hours after the module is unpacked and the firmware is burned. If not, vacuum pack the module again. Bake the module before mounting components to the module.
 - (1) SMT placement equipment
 - i. Reflow soldering machine
 - ii. Automated optical inspection (AOI) equipment
 - iii. Nozzle with a 6 mm to 8 mm diameter

- (2) Baking equipment
 - i. Cabinet oven
 - ii. Anti-static heat-resistant trays
 - iii. Anti-static heat-resistant gloves
2. Storage conditions for a delivered module are as follows:
 - (1) The moisture-proof bag is placed in an environment where the temperature is below 30°C and the relative humidity is lower than 70%.
 - (2) The shelf life of a dry-packaged product is six months from the date when the product is packaged and sealed.
 - (3) The package contains a humidity indicator card (HIC).

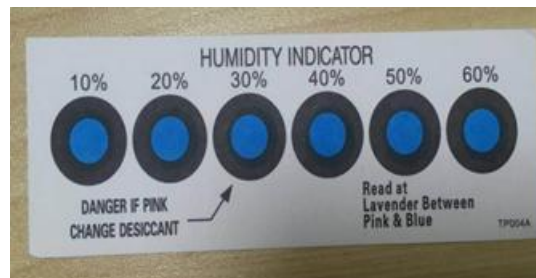


Figure 7-5 HIC for WBR3D

3. Bake a module based on HIC status as follows when you unpack the module package:
 - (1) If the 30%, 40%, and 50% circles are blue, bake the module for 2 consecutive hours.
 - (2) If the 30% circle is pink, bake the module for 4 consecutive hours.
 - (3) If the 30% and 40% circles are pink, bake the module for 6 consecutive hours.
 - (4) If the 30%, 40%, and 50% circles are pink, bake the module for 12 consecutive hours.
4. Baking settings:
 - (1) Baking temperature: 125±5°C
 - (2) Alarm temperature: 130°C
 - (3) SMT placement ready temperature after natural cooling: < 36°C
 - (4) Number of drying times: 1

- (5) Rebaking condition: The module is not soldered within 12 hours after baking.
5. Do not use SMT to process modules that have unpacked for over three months. Electroless nickel immersion gold (ENIG) is used for the PCBs. If the solder pads are exposed to the air for over three months, they will be oxidized severely and dry joints or solder skips may occur. Tuya is not liable for such problems and consequences.
 6. Before SMT placement, take electrostatic discharge (ESD) protective measures.
 7. To reduce the reflow defect rate, draw 10% of the products for visual inspection and AOI before first SMT placement to determine a proper oven temperature and component placement method. Draw 5 to 10 modules every hour from subsequent batches for visual inspection and AOI.

7.4 Recommended Oven Temperature Curve

Perform SMT placement based on the following reflow oven temperature curve. The highest temperature is 245°C.

Refer to IPC/JEDEC standard ; Peak Temperature : <250°C ; Number of Times: ≤2 times ;

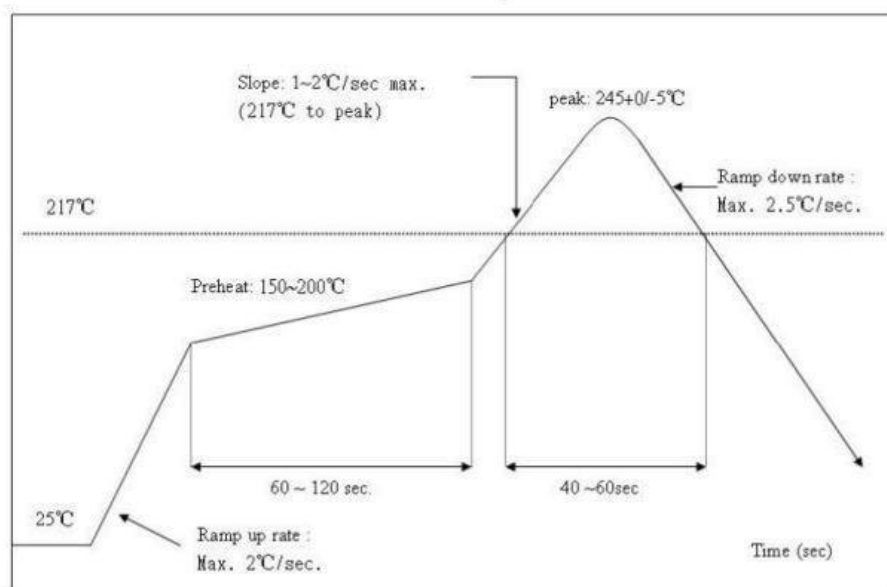


Figure 7-6 Oven temperature curve

7.5 Storage Conditions

	CAUTION This bag contains MOISTURE-SENSITIVE DEVICES	LEVEL 3
	If Blank, see adjacent bar code label	
1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH)		
2. Peak package body temperature: <u>260</u> °C If Blank, see adjacent bar code label		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must		
a) Mounted within: <u>168</u> hrs. of factory conditions If Blank, see adjacent bar code label		
≤ 30°C/60%RH, OR		
b) Stored at <10% RH		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card is > 10% when read at 23 ± 5°C		
b) 3a or 3b not met.		
5. If baking is required, devices may be baked for 48 hrs. at 125 ± 5°C		
Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: _____ If Blank, see adjacent bar code label		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

Appendix: Statement

Federal Communications Commission (FCC) Declaration of Conformity

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled rolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator and your body.

The final end product must be labeled in a visible area with the following: "Contains Transmitter Module 2ANDL-WBR3D"

This radio module must not installed to co-locate and operating simultaneously with other radios in host system except in accordance with FCC multi-transmitter product procedures. Additional testing and equipment authorization may be required to operating simultaneously with other radio.

The availability of some specific channels and/or operational frequency bands are country dependent and are firmware programmed at the factory to match the intended destination. The firmware setting is not accessible by the end user.

The host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification. The final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed. The end user manual shall include all required regulatory information/warning as shown in this manual, including: This product must be installed and operated with a minimum distance of 20 cm between the radiator and user body.

Declaration of Conformity European notice



Hereby, Hangzhou Tuya Information Technology Co., Ltd. declares that this module product is in compliance with essential requirements and other relevant provisions of Directive 2014/53/EU. A copy of the Declaration of conformity can be found at <https://www.tuya.com>.

The device is restricted to indoor use only when operating in the 5150 to 5350 MHz frequency range.

	AT	BE	BG	HR	CY	CZ	DK
	EE	FI	FR	DE	EL	HU	IE
	IT	LV	LT	LU	MT	NL	PL
	PT	RO	SK	SI	ES	SE	UK



This product must not be disposed of as normal household waste, in accordance with EU directive for waste electrical and electronic equipment (WEEE- 2012/19/EU). Instead, it should be disposed of by returning it to the point of sale, or to a municipal recycling collection point.